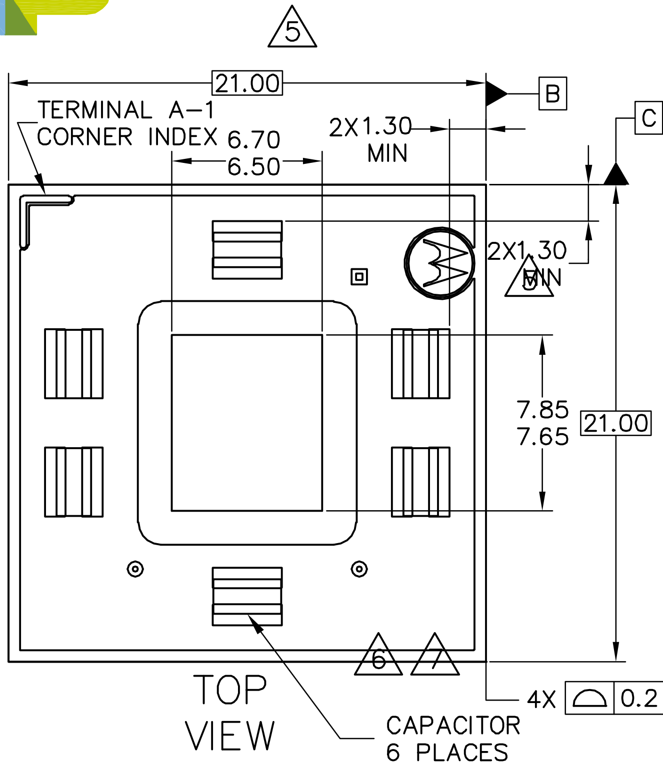

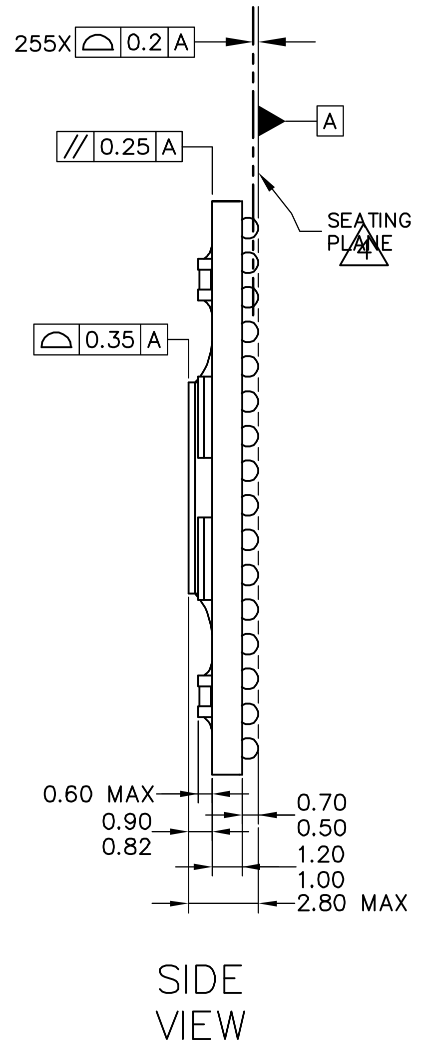

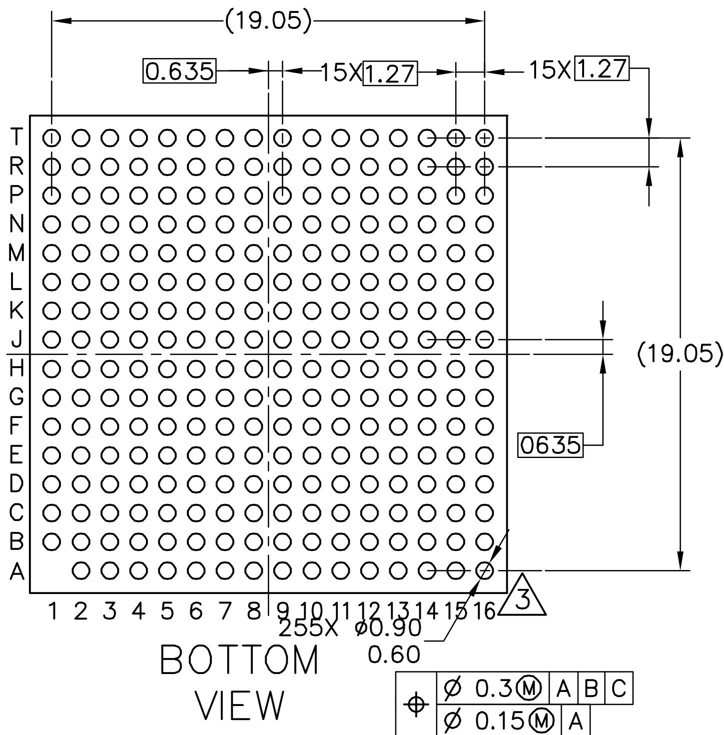

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TITLE: 255 FC−PBGA, 21 X 21 1.27 PITCH	DOCUMENT NO: 98ARS23993W REV: B	
	STANDARD: JEDEC MO−151 BAH−1	
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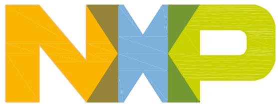

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

2. DIMENSIONS IN MILLIMETERS.

△3 DIMENSION IS THE MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

△4 DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5 DIMENSIONS ARE THE MINIMUM CLEARANCE FROM THE PACKAGE EDGE TO THE CHIP CAPACITORS.

△6 CAPACITORS SIZE IS 0612. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

△7 CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

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